Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards@onsemi.com Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Uni	ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
Company name* Company unique ID Unique ID Authority Response Date* 2025-06-05 Contact Name Title - Contact* Product Enviro Compliance NA Product-Env-Stewards Authorized Representative* Title - Representative Title - Representative Product Enviro Compliance NA Product-Env-Stewards NA Product-Env-Stewards Product-Env-Stewards Nanufacturing Site Weight* UOM Uni Uni Uni Product-Env-Stewards Nanufacturing Site Weight* UOM Uni Vanufacturing Proccess Information Vanufacturing Proccess Information Product-Env-Stewards Nanufacturing Site Weight* Womper of Reflow Cycles Max Time at Peak Temperature Number of Reflow Cycles Matter Tin (Sn) - annealed CU Alloy 1 260 C 30 Seconds 3	752-21.1										ials and Mf	g Informat	ion		
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Authorized Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number Mfr Item Numbe	ontact Name		Title - Contact			1	Phone - Contact*				Email - Contact*				
Product-Env-Stewards Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Uni NUP2201MR6T1G MI TSOP6 MICRO TVS/RECT 2025-06-05 TH2 13.43 mg Eac Manufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Term	Product-Env-Stewa	rds		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	Authorized Representative* Title				Fitle - Representative			Phone - Representative*			Email - Representative*				
NUP2201MR6T1G MI TSOP6 MICRO TVS/RECT 2025-06-05 TH2 13.43 mg Eac Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles and Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Product-Env-Stewar	rds		Product Env	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Anufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Requester	Requester Item Number M		Mfr Item Number Mfr Item Name			Effe		Version	. I	Manufacturing Site	V	Veight*	UOM	Unit Type
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3			NUP2201	MR6T1G	MI TSOP6 MICRO) TVS/RECT		2025-06-05		7	ГН2	1	3.43	mg	Each
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3 comments				orminal Pess	Alloy	STD 020 MS1	Dating	Dook Proc	noss Poder	Comporative	ro May Time at Peak	Tomporet	uro Nuest	har of Paflow Cov	alac
omments					Alloy J-	8 I D-020 MSI	L Kanng		cess Body 1	T .				ber of Reflow Cyc	cies
	•	i (Sii) - anneaied	C	U Alloy	I			200		JC	30	second	18 3		
ver 1 - maximum time at peak temperature during soldering is 10-50 seconds		me at neels towners t	dunina c-1	domina ia 10-1	20 seconds										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detail	ed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a		
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct at it in member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.67	mg	Supplier	Silicon (Si)	7440-21-3		0.67	mg
Die Attach	0.15	mg	Supplier	Silver (Ag)	7440-22-4		0.1125	mg
			Supplier	Epoxy resins	129915-35-1		0.0375	mg
Lead Frame	2.4	mg	Supplier	Silver (Ag)	7440-22-4		0.0696	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0029	mg
			Supplier	Iron (Fe)	7439-89-6		0.0564	mg
			Supplier	Copper (Cu)	7440-50-8		2.2704	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0007	mg
Mold Compound-Black	10.0	mg		Brominated epoxy resin	proprietary data		1.39	mg
			Supplier	Phenolic Resin	Proprietary Data		0.88	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.18	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		5.79	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		1.76	mg
Plating	0.13	mg	Supplier	Tin (Sn)	7440-31-5		0.13	mg
Wire Bond - Au	0.08	mg	Supplier	Gold (Au)	7440-57-5		0.08	mg